

FFSP3065B

Silicon Carbide Schottky Diode

650 V, 30 A

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 144 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuit

ABSOLUTE MAXIMUM RATINGS

(T_C = 25°C, Unless otherwise specified)

Symbol	Parameter	Value	Unit
V _{RRM}	Peak Repetitive Reverse Voltage	650	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)	144	mJ
	Continuous Rectified Forward Current @ T _C < 135°C	30	
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	A
		T _C = 150°C, 10 μs	
I _{F, SM}	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	A
P _{tot}	Power Dissipation	T _C = 25°C	W
		T _C = 150°C	
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +175	°C

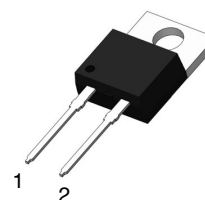
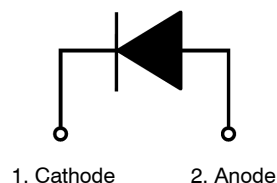
1. E_{AS} of 144 mJ is based on starting T_J = 25°C, L = 0.5 mH, I_{AS} = 24 A, V = 50 V.



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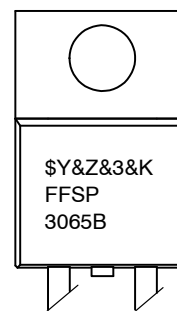
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ELECTRICAL CONNECTION



TO-220-2LD
CASE 340BB

MARKING DIAGRAM



\$Y = ON Semiconductor Logo
&Z = Assembly Plant Code
&3 = Numeric Date Code
&K = Lot Code
FFSP3065B = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

FFSP3065B

THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.76	$^{\circ}\text{C}/\text{W}$

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FFSP3065B	FFSP3065B	TO220	Tube	N/A	N/A	50 Units

ELECTRICAL CHARACTERISTICS $T_C = 25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Forward Voltage	$I_F = 30\text{ A}, T_C = 25^{\circ}\text{C}$		1.38	1.7	V
		$I_F = 30\text{ A}, T_C = 125^{\circ}\text{C}$		1.6	2.0	
		$I_F = 30\text{ A}, T_C = 175^{\circ}\text{C}$		1.72	2.4	
I_R	Reverse Current	$V_R = 650\text{ V}, T_C = 25^{\circ}\text{C}$		0.5	40	μA
		$V_R = 650\text{ V}, T_C = 125^{\circ}\text{C}$		1.0	80	
		$V_R = 650\text{ V}, T_C = 175^{\circ}\text{C}$		2.0	160	
Q_C	Total Capacitive Charge	$V = 400\text{ V}$		74		nC
C	Total Capacitance	$V_R = 1\text{ V}, f = 100\text{ kHz}$		1280		pF
		$V_R = 200\text{ V}, f = 100\text{ kHz}$		139		
		$V_R = 400\text{ V}, f = 100\text{ kHz}$		108		

TYPICAL CHARACTERISTICS $T_J = 25^\circ\text{C}$ Unless Otherwise Noted

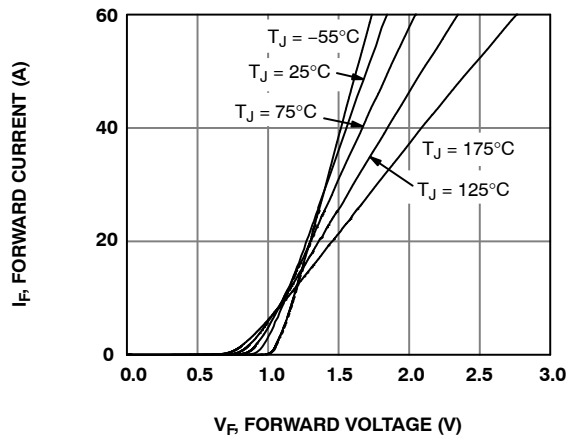


Figure 1. Forward Characteristics

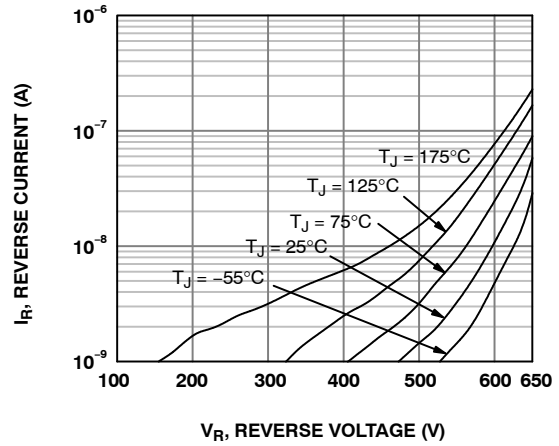


Figure 2. Reverse Characteristics

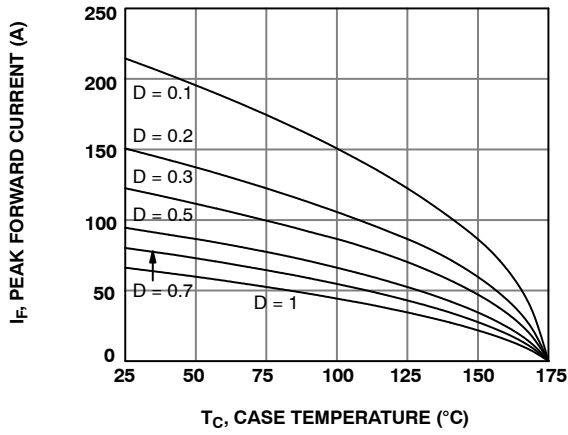


Figure 3. Current Derating

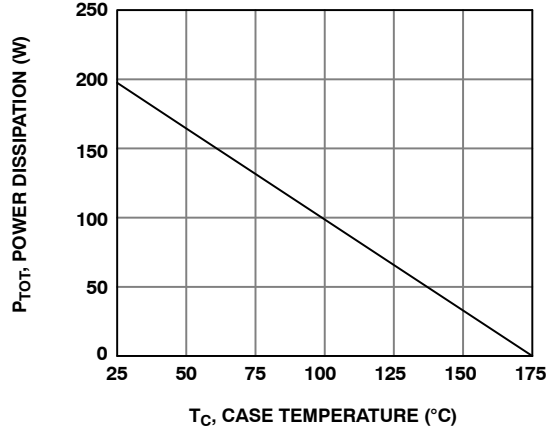


Figure 4. Power Dissipation

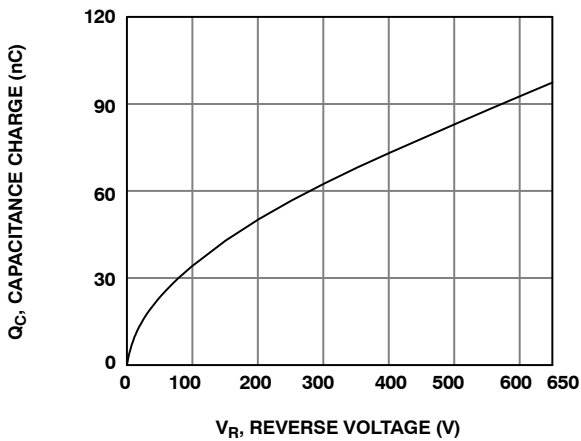


Figure 5. Capacitance Charge vs. Reverse Voltage

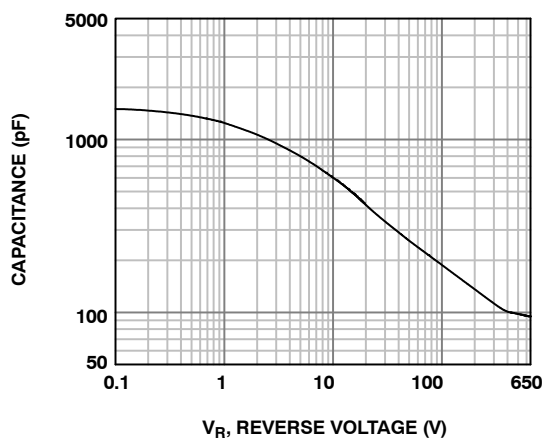


Figure 6. Capacitance vs. Reverse Voltage

TYPICAL CHARACTERISTICS $T_J = 25^\circ\text{C}$ Unless Otherwise Noted (continued)

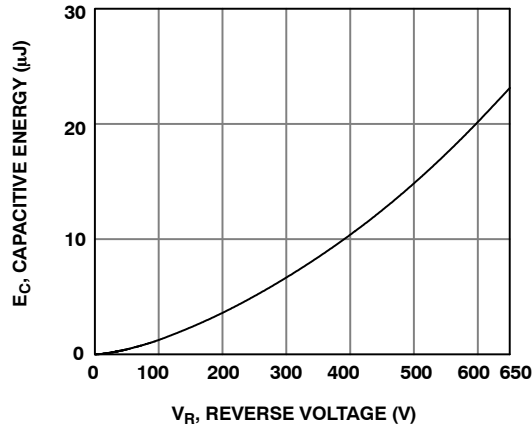


Figure 7. Capacitance Stored Energy

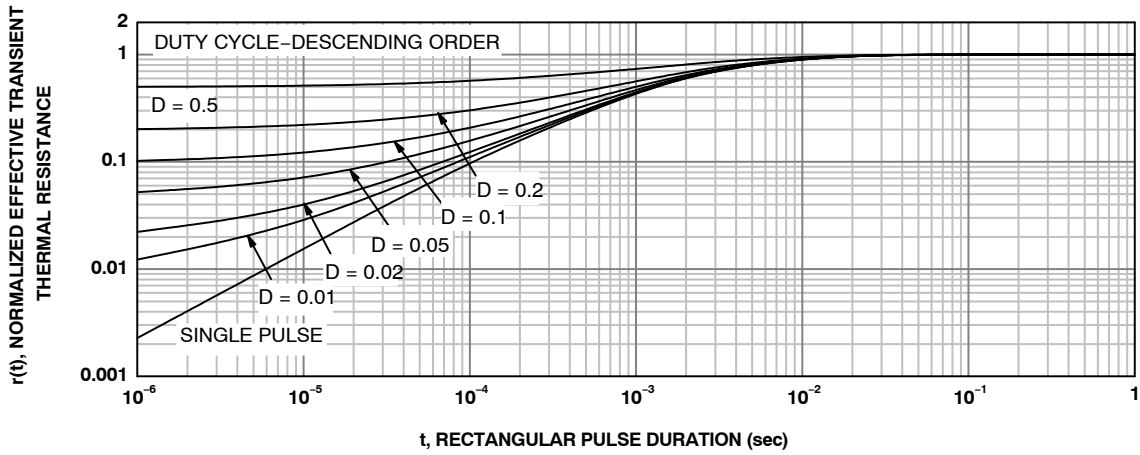


Figure 8. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS

$L = 0.5 \text{ mH}$
 $R < 0.1 \Omega$
 $V_{DD} = 50 \text{ V}$

$E_{AVL} = 1/2 L I_2^2 [V_{R(AVL)} / (V_{R(AVL)} - V_{DD})]$
 $Q1 = \text{IGBT (} BV_{CES} > \text{DUT } V_{R(AVL)} \text{)}$

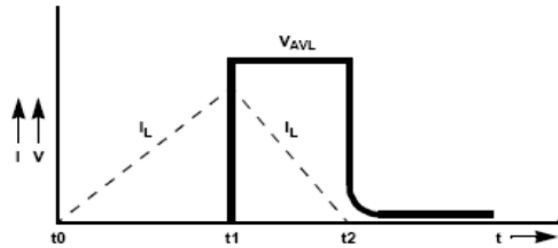
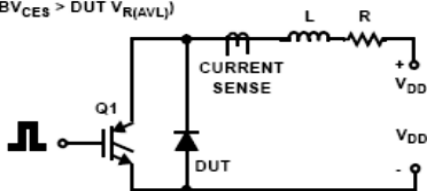


Figure 9. Unclamped Inductive Switching Test Circuit & Waveform

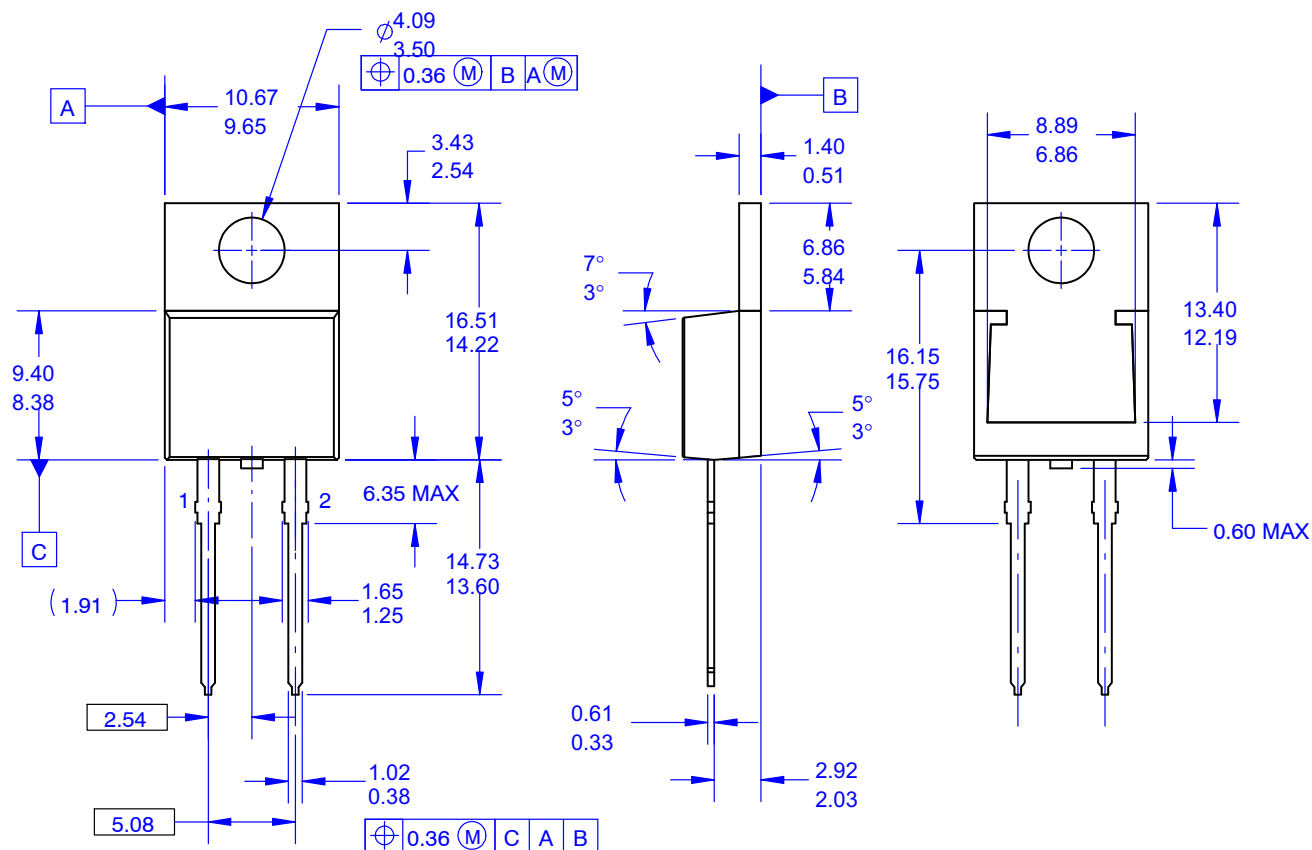
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



TO-220-2LD
CASE 340BB
ISSUE O

DATE 31 AUG 2016



NOTES:

- PACKAGE REFERENCE: JEDEC TO220,ISSUE K, VARIATION AC,DATED APRIL 2002.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

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